BS EN IEC 61249-2-51:2023

BSI Standards Publication

# Materials for printed boards and other interconnecting structures

Part 2-51: Reinforced base materials, clad and unclad — Base materials for integrated circuit card carrier tape, unclad

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# National foreword

This British Standard is the UK implementation of EN IEC 61249-2-51:2023. It is identical to IEC 61249-2-51:2023.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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EUROPEAN STANDARD

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EUROPÄISCHE NORM

# EN IEC 61249-2-51

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English Version

# Materials for printed boards and other interconnecting structures - Part 2-51: Reinforced base materials, clad and unclad - Base materials for integrated circuit card carrier tape, unclad (IEC 61249-2-51:2023)

Matériaux pour circuits imprimés et autres structures d'interconnexion - Partie 2-51: Matériaux de base renforcés, plaqués et non plaqués - Matériaux de base pour bande support de carte à circuit intégré, non plaqués (IEC 61249-2-51:2023)

Werkstoffe für Leiterplatten und andere Verbindungsstrukturen - Teil 2-51: Kaschierte und unkaschierte verstärkte Basismaterialien - Basismaterial als Chipträger, nicht kaschiert (IEC 61249-2-51:2023)

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# European foreword

The text of document 91/1847/FDIS, future edition 1 of IEC 61249-2-51, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61249-2-51:2023.

The following dates are fixed:

| | | |
|---|---|---|
| • latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement | (dop) | 2024-03-15 |
| • latest date by which the national standards conflicting with the document have to be withdrawn | (dow) | 2026-06-15 |

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## Endorsement notice

The text of the International Standard IEC 61249-2-51:2023 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standard indicated:

ISO 9000 NOTE Approved as EN ISO 9000

ISO 14001 NOTE Approved as EN ISO 14001

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# Annex ZA
(normative)

## Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

| Publication | Year | Title | EN/HD | Year |
|---|---|---|---|---|
| IEC 61189-2 | 2006 | Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2: Test methods for materials for interconnection structures | EN 61189-2 | 2006 |
| IEC/PAS 61249-6-3 | - | Specification for finished fabric woven from "E" glass for printed boards | - | - |
| ISO 2813 | - | Paints and varnishes - Determination of gloss value at 20°, 60° and 85° | EN ISO 2813 | - |
| ISO 8296 | - | Plastics - Film and sheeting - Determination of wetting tension | - | - |
| ISO 11014 | 2009 | Safety data sheet for chemical products - Content and order of sections | - | - |
| ISO 21920-2 | - | Geometrical product specifications (GPS) - Surface texture: Profile - Part 2: Terms, definitions and surface texture parameters | EN ISO 21920-2 | - |
| ASTM D 882 | - | Standard Test Method for Tensile Properties of Thin Plastic Sheeting | - | - |

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